

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|-------|-----------------------------------------------------------------------------------------------------------------------------------------------------------|---------------------------------------------------------|------------------|---------|------------------|
| L1 | 25614 | (element or chip or ic or component or die or dye or device) with (curv\$3 or blend\$3 or flexible) with (substrate or wafer) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 10:10 |
| L2 | 1454 | 1 and (transfer\$3 with method) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 09:54 |
| L3 | 163 | 2 and (second) near (wafer or method) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 09:54 |
| L4 | 659 | (element or chip or ic or component or die or dye or device) with (curv\$3 or blend\$3 or flexible) with (second) near (substrate or wafer) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 09:54 |
| L5 | 51 | 4 and (transfer\$3 with method) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 09:54 |
| L6 | 29505 | (element or chip or ic or component or die or dye or device) and (curv\$3 or blend\$3 or flexible) and (substrate or wafer) and (transfer\$3 with method) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 10:11 |
| L7 | 14009 | 6 and (element or chip or ic or component or die or dye or device) with (substrate or wafer) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 10:12 |
| L8 | 1382 | 6 and (element or chip or ic or component or die or dye or device) with (second) near3 (substrate or wafer) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 10:13 |
| L9 | 747 | 6 and (element or chip or ic or component or die or dye or device) with (second) near (substrate or wafer) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 10:13 |

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|-----|-----|---------------------------------------------------------------------------------------------------------------------------------------------------|---------------------------------------------------------|----|----|------------------|
| L10 | 449 | 6 and (element or chip or ic or component or die or dye or device) with (second) near (substrate or wafer) same (first) near (wafer or substrate) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/15 10:13 |
|-----|-----|---------------------------------------------------------------------------------------------------------------------------------------------------|---------------------------------------------------------|----|----|------------------|